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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT

In re application of: O'DONNELL

Attorney Docket No.:
LAM1P133/P0582

Application No.: 09/472,757

Examiner: Umez Eronini, Lynette T.

Filed: December 27, 1999

Group: 1765

Title: INSITU POST ETCH PROCESS TO
REMOVE REMAINING PHOTORESIST AND
RESIDUAL SIDEWALL PASSIVATION

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail to: Box Non-Fee Amendment, Commissioner for Patents, Washington, D.C. 20231 on October 9, 2002.

Signed: _____

Sue Funchess
Sue Funchess

AMENDMENT C

Box Non-Fee Amendment
Commissioner for Patents
Washington, D.C. 20231

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Dear Madame:

This is in response to the office action mailed July 31, 2002. Please consider the following remarks and amend the above-identified patent application as follows:

In the Claims:

Please add new claims 19 and 20 and amend claim 17, as follows:

17. (Once Amended) The method, as recited in claim 1, wherein the stripping away the etch mask and removing some residual sidewall passivation, simultaneously strips away the etch mask and removes [comprises removing] parts of the metal-containing layer that are redeposited to form residual sidewall passivation.

19. (New) The method, as recited in claim 1, wherein the stripping away the etch mask and removing some sidewall passivation comprises removing metal containing parts of the metal-containing layer that are redeposited to form residual sidewall passivation.